

Applicants : Hans Krueger, et al.  
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Filed : Herewith  
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Attorney's Docket No.: 14219-076US1  
Client's Ref.: P2002,0686USN

**AMENDMENTS TO THE SPECIFICATION:**

Please add the following centered heading at page 1, line 2:

**TECHNICAL FIELD**

Please add the following centered heading at page 1, line 13:

**BACKGROUND**

Please add the following centered heading at page 2, line 19:

**SUMMARY**

Please add the following centered heading at page 16, line 6:

**DESCRIPTION OF THE DRAWINGS**

Please add the following centered heading at page 17, line 4:

**DETAILED DESCRIPTION**

Please replace the Abstract on page 43 with the following new Abstract:

A component includes a chip having a top surface and having a bottom surface that includes electrically conductive structures, and a carrier substrate having a top surface that includes connecting areas. The chip is mounted in a flip chip arrangement on the carrier substrate via electrically conductive connections between the electrically conductive

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structures and the connecting areas. A support element is on the top surface of the carrier substrate. The support element surrounds the carrier substrate but does not touch the carrier substrate. A seal surrounds the chip and the support element. The support element supports the seal.

Please delete the phrase "Figure 1" at page 43, line 18.